APPROVAL SHEET

To：

Customer P/N：

UDE P/N： SS10-ZZ-0019

Description： SFP+ Cage 1X1

DIP

With Heatsink

Packing With Tray

RoHS

Spec No.	Update Date	Revision
SS1021014-00	2021/5/29	A

Approved	Checked	Prepared

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Revision History

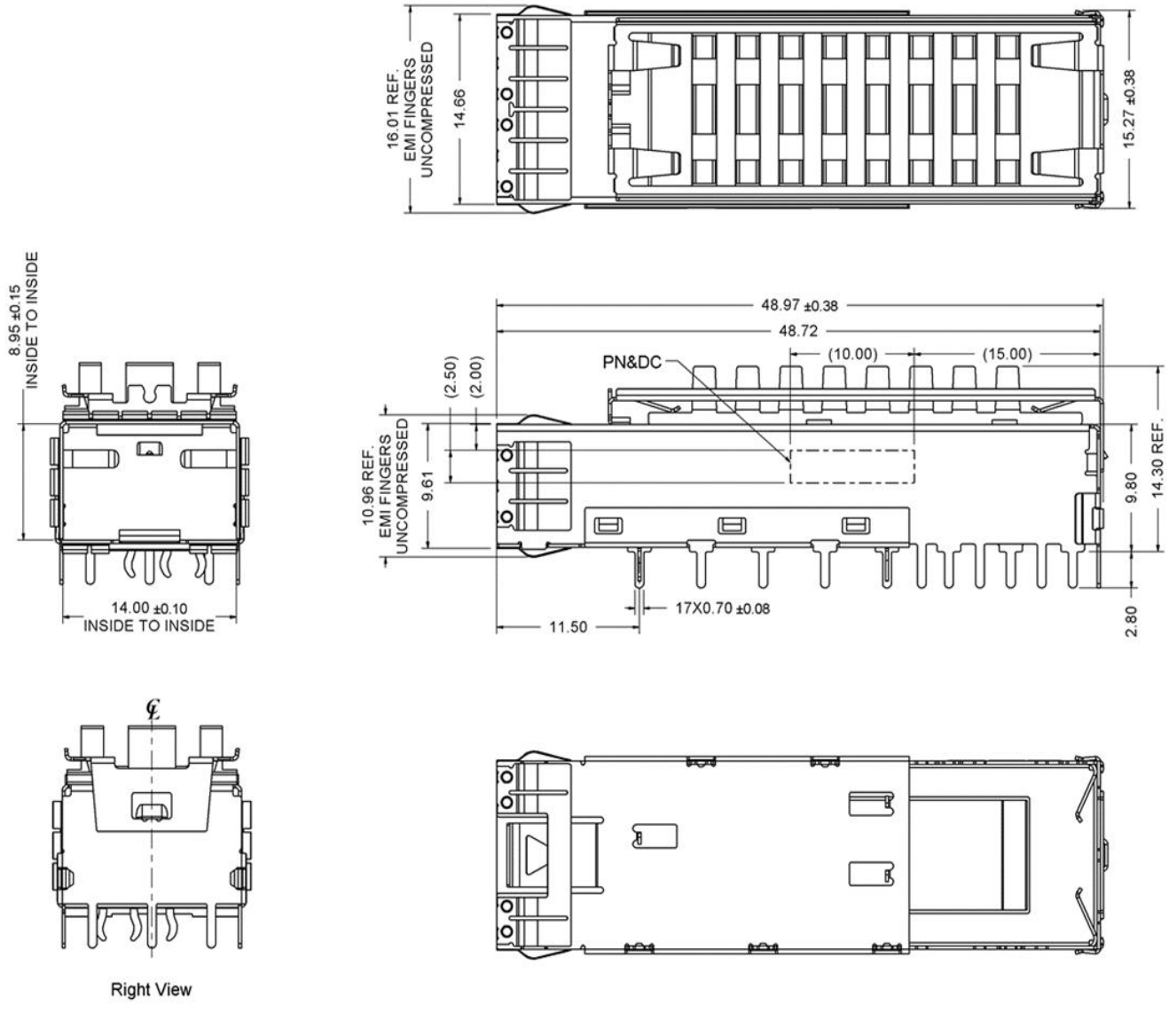
Issue Date	Revision	Comments	Operator
2021/5/29	A	Initial Release .	Mars

UD-P09-R03E

1. MECHANICAL DIMENSION

Product Dimension

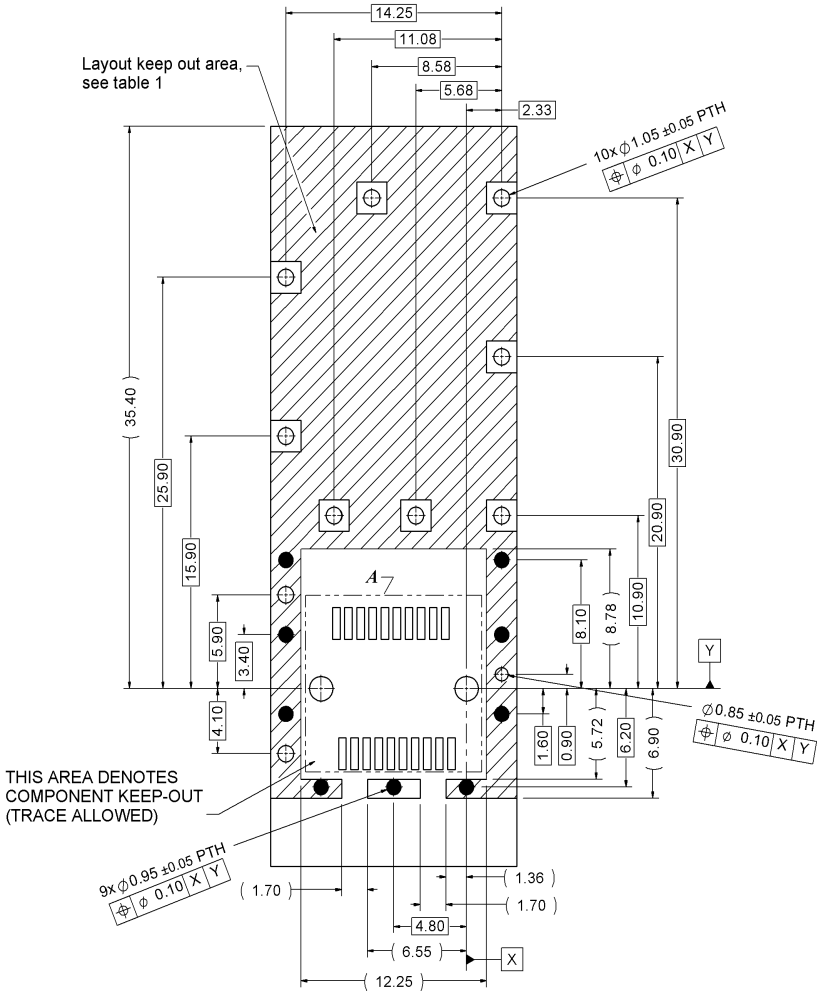
Unit:mm	General Tolerance :	X.X : ± 0.38 X.XX : ± 0.20

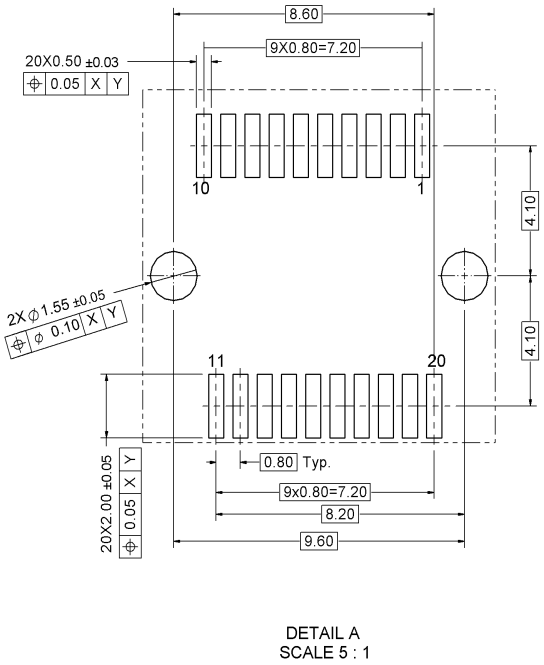


2. Recommended PCB Layout.Component Side of Board

All dimension units are "mm".

All dimension tolerances are ±0.05mm unless otherwise specified





DETAIL A
SCALE 5 : 1

NOTES:

1.PADS AND VIAS CONNECT TO CHASSIS GROUND

RECOMMEND PADS TO BE 2.00mm SQUARE

2.RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

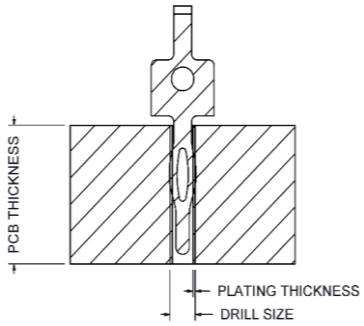
3.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.

Layout / Layer	Trace	component	Grounding	Test Point	Via Hole	PTH	NPTH
Component side	X	X	O	X	X	X	O
Inner layer	O	NA	O	NA	O	X	O
Bottom side	O	O	O	O	O	X	O

X--Forbid; O--OK; NA--Not Applicable.

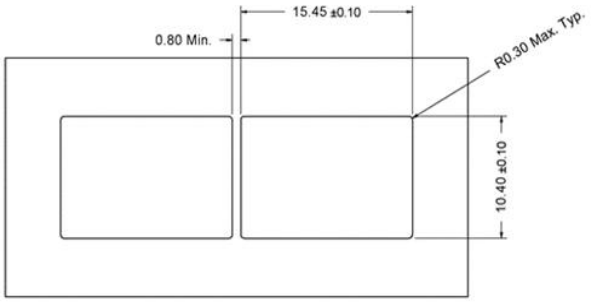
RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

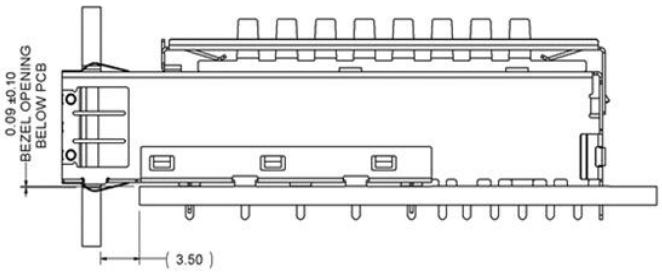
PLATED THROUGH HOLE	1.05 SHIELD PINS	0.95 SHIELD PINS	0.85 SHIELD PINS
FINISHED HOLE DIAMETER	1.05±0.05	0.95±0.05	0.85±0.05
DRILLED HOLE DIAMETER	1.15	1.05	0.95
COPPER PLATING	0.025 Min.	0.025 Min.	0.025 Min.



RECOMMENDED MOTHER BOARD
THROUGH HOLE DIMENSION

3. Recommended Panel cutout





PRESS-FIT ASSEMBLIES
Hand place using proper seating force to engage all Leg tails into plated thru-holes.

Assemblies are to be seated per the instructions associated with the appropriate insertion tool
Note:UDE recommends only one connector assembly be installed at a time.

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
1X1	Copper w/OSP	220±20N

4. Packing Information

20 pcs finished goods per tray

6 trays(120pcs finished goods) per master carton

5. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Shield Parts

Top Shell : Copper Alloy, Thickness=0.25mm

Bottom Shell : Copper Alloy, Thickness=0.25mm

EMI Spring Finger : Ph.Bronze, Thickness=0.08mm

Finish : 30μ" min. Nickel

Heatsink Clip: Stainless steel,Thickness=0.25mm

Heatsink: Aluminum Alloy

Finish : Black oxide coating

6. Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : - 55°C+105°C

7. SFP CAGE specifications

Insertion force: 18 N max at a max. rate of 25.4mm per minute
(SFP module to SFP cage)(without heatsink)

Extraction force : 12.5 N max at a max. rate of 25.4mm per minute
(SFP module to SFP cage)(without heatsink)

Cage Retention (Latch strength) : 90N Min.

Durability : 100 cycles for standard class

8. Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table.

All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

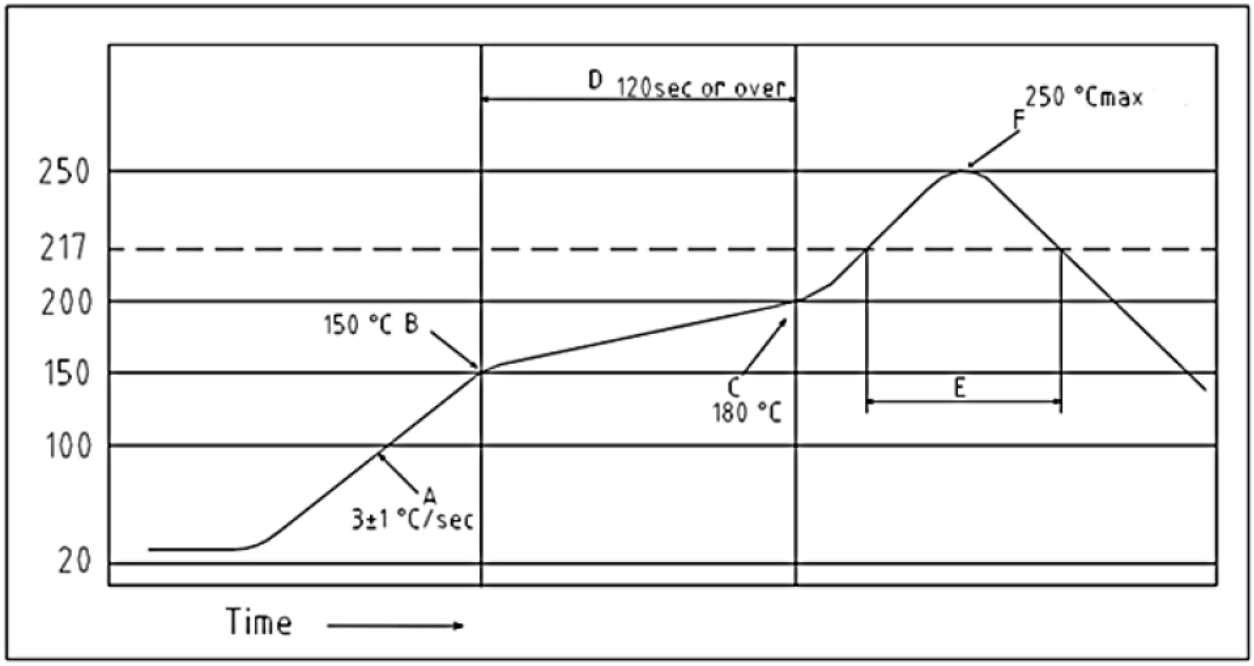
9. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

10. IR REFLOW TEMPERATURE PROFILE

Temperature condition of reflow soldering

Contents	Soldering Condition
A：Increasing speed	3±1°C/sec
B：Pre-heat starting Temp	150°C
C：Pre-heat ending Temp	180°C
D：Pre-heat interval	120 sec or over
E：Over 217°C time	60～150 sec
F：Peak Temperature	250°C max. 10sec



Type of lead-free solder should be 96.5Sn-3.0Ag-0.5Cu or 99.3Sn-0.7Cu.